Smart3 platform can load any type of data to enable collaborative IA through three applicative modules. Typical applications of SmartMet3 gather the analysis of Transmission Electron Microscopy cross sections for advance nodes or layout analysis from top view Scanning Electron Microscopy for design validation. For SmartDef3, defectivity analysis can be performed at both wafer and pattern levels allowing strong versatility of analysis. Finally, SmartYield3 enables the creation of digital twins of process to freely explore them in addition to specific methods to find optimal process recipes from a model.

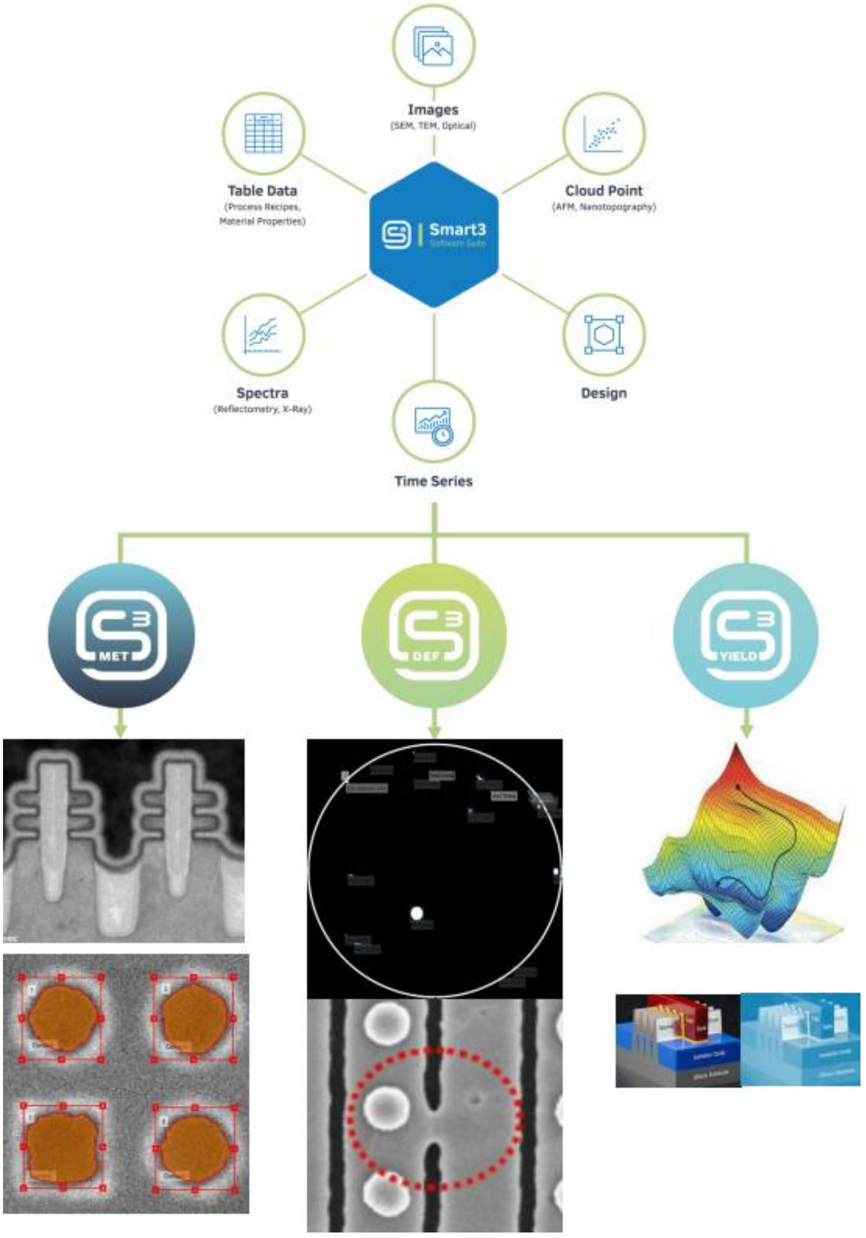

Figure 1: Illustration of Data Flow and various applications that can be analyzed with SmartMet3, SmartDef3 and SmartYield3